MA3D693 (MA6D93)

Silicon planar type

For high-frequency rectification

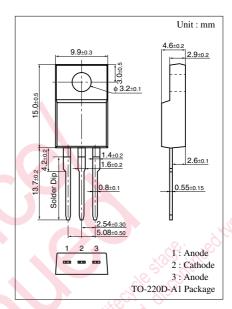
■ Features

- Low forward rise voltage V_F
- Fast reverse recovery time t_{rr}
- \bullet TO-220D (Full-pack package) with high dielectric breakdown votlage $> 5.0~\rm{kV}$
- Easy-to-mount, caused by its V cut lead end

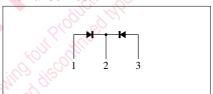
■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	V _{RRM}	400	V
Non-repetitive peak reverse surge voltage	V _{RSM}	400	v
Average forward current	I _{F(AV)}	5	A
Non-repetitive peak forward surge current*	I _{FSM}	45	A
Junction temperature	$T_{\rm j}$	-40 to +150	°C
Storage temperature	T _{stg}	-40 to +150	°C

Note) * : Half sine-wave; 10 ms/cycle



Internal Connection

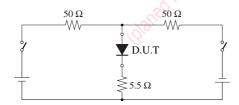


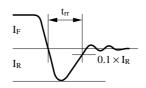
■ Electrical Characteristics $T_a = 25$ °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Repetitive peak reverse current	I_{RRM1}	$V_{RRM} = 400 \text{ V}, T_{C} = 25^{\circ}\text{C}$			50	μΑ
	I_{RRM2}	$V_{RRM} = 400 \text{ V}, T_j = 150^{\circ}\text{C}$			3	mA
Forward voltage (DC)	$V_{\rm F}$	$I_F = 2.5 \text{ A}, T_C = 25^{\circ}\text{C}$			1	V
Reverse recovery time*	t _{rr}	$I_F = 1 A, I_R = 1 A$			100	ns
Thermal resistance	R _{th(j-c)}	Direct current (between junction and case)			3.3	°C/W
	R _{th(j-a)}	5			62.5	°C/W

Note) 1. Rated input/output frequency: 10 MHz

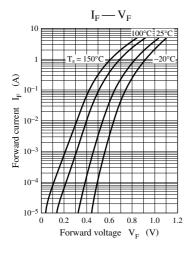
2. *: t_{rr} measuring circuit

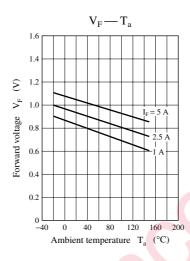


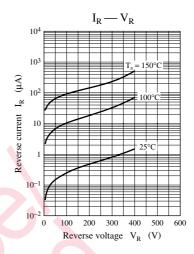


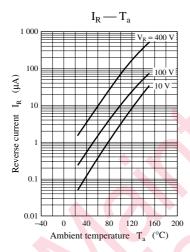
Note) The part number in the parenthesis shows conventional part number.

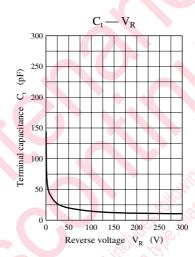
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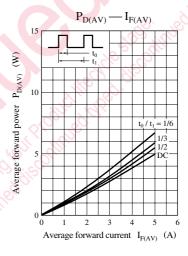


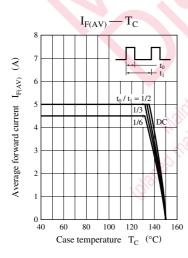












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